

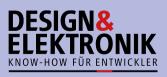
Nuremberg, Germany 26.-28.2.2019



CONFERENCE PROGRAM

www.embedded-world.eu

Organized by



design-elektronik.de

NÜRNBERG MESSE

pls











7.4 MILLION+ PRODUCTS ONLINE | 750+ INDUSTRY-LEADING SUPPLIERS | 1,300,000+ PRODUCTS IN STOCK

The World's Largest Selection of Electronic Components Available for Immediate Dispatch[™]



TELEPHONE: 0800 180 01 25



100% FRANCHISED

*A shipping charge of € 18.00 will be billed on all orders of less than € 50.00. A shipping charge of \$22.00 USD will be billed on all orders of less than \$60.00 USD. All orders are shipped via UPS, Federal Express, or DHL for delivery within 1-3 days (dependent on final destination). No handling fees. All prices are in euro or United States dollar. Digi-Key is a franchised distributor for all supplier partners. New product added daily. Digi-Key and Digi-Key Electronics are registered trademarks of Digi-Key Electronics in the U.S. and other countries. © 2018 Digi-Key Electronics, 701 Brooks Ave. South, Thief River Falls, MN 56701, USA





embedded world Conference 2019 – Embedded Intelligence

Prof. Dr.-Ing. Axel Sikora Chairman of embedded world Conference

Now in its 17th year, the embedded world Conference takes up the title of one of its precursors from the 1990s. Back then "Embedded Intelligence" was rather a vision of the future but now it is increasingly becoming reality and shaping more and more systems: from autonomous vehicles over image recognition and embedded vision systems to preventive and demand-driven maintenance in Industry 4.0 systems, from small edge computers to high-performance cloud servers. These developments not only open up immense possibilities and business opportunities, but are also closely associated with many technical, economic, social and ethical issues.

With a program of high-quality and solution-oriented presentations, the embedded world Conference 2019 aims to contribute once more to the success of an industry that has now become an essential part of the technological future and, as such, a basis for our continued economic success.

The embedded world Conference 2019 is made up of 10 subject areas, which are clearly structured in the program and presented in different colors. These are: 1. Internet of Things, 2. Connected Systems, 3. Embedded OS, 4. Safety & Security, 5. Hardware Engineering, 6. Software &

Systems Engineering, 7. Embedded Vision, 8. Autonomous & Intelligent Systems, 9. Embedded GUI & HMI, and 10. System-on-Chip. The solution-oriented presentations of each session build upon one another and examine questions from different perspectives. Discussion and an active exchange of ideas with the speakers as well as among conference participants are encouraged. The 30-minute presentations of the sessions will be complemented by 12 classes, which provide comprehensive basic information on selected topics in the form of condensed training courses.

It is not possible to describe all 250 presentations in detail here. You will find them fully explained on the following pages of this booklet.

The steering board of the embedded world Conference 2019 wishes all participants stimulating discussions about new ideas and solutions in order to be able to cope more easily and better with the immense challenges that lie ahead. You are welcome to gain great insights in a pulsating atmosphere.

Prof. Dr.-Ing. Axel Sikora Chairman of embedded world Conference

	1. Internet of Things							
	– Platforms & Applications	2. Connecte	d Systems		3. Embedded OS		4. Safety 8	r Security
DAY 1: morning		Session 2.1: Communication I CAN	Session 2.2: Communication II Bluetooth	Session 3.1: OS Basics	Class 3.1: The Robert Berger Class: Embedded Linux – a Crash Course		Session 4.1 I: HW-based Security I	Session 4.2: Functional Safety
DAY 1: afternoon		Session 2.3: Communication III Realtime & TSN		Session 3.2: OSADL			Session 4.1 II: HW-based Security II	
DAY 2: morning	Session 1.1 I: IoT I	Session 2.4: Communication IV Wireless Physical & Design Aspects		Session 3.3: Linux	Class 3.2: Embedded Android Workshop		Session 4.3 I: Security Architectures & Hacking I	Class 4.1: The ESCRYPT Class
DAY 2: afternoon	Session 1.1 II: IoT II	Session 2.5: Communication V Wireless Multiprotocol		Session 3.4: Virtualization		Class 3.3: Linux Hands-on Workshop with BeagleBoard.org PocketBeagle	Session 4.3 II: Security Architectures & Hacking II	
DAY 3: morning	Session 1.2: IoT III	Session 2.6 I: NB-IoT & LPWA I	Session 2.8 l: Wireless Power I	Session 3.5: OS-Security	Class 3.4: The Mc Guire Class: Introduction to Linux Kernel Tools		Session 4.4 l: Securing IoT I	
DAY 3: afternoon	Session 1.3: IoT IV OPC UA I 4.0	Session 2.6 II: NB-IoT & LPWA II	Session 2.8 II: Wireless Power II				Session 4.4 II: Securing IoT II	Class 4.2: Hands-on Side Channel Power
		Session 2.7: Communication VI Wireless Localization						Analysis

KEYNOTE-SPEAKERS



Jim Tung, MathWorks Conference Keynote: Developing Game-Changing Embedded Intelligence February 26th, 2019, 1:30 PM

Jim Tung is a MathWorks Fellow, focusing on business and technology strategy and working with key customers and partners. Jim has more than 35 years of experience in real-time systems, data acquisition, and technical computing, including 30 years at MathWorks. Jim was previously vice president of marketing and vice president of business development at MathWorks, and earlier held marketing and sales management positions at Lotus Development and Keithley DAS, a pioneering manufacturer of PC-based data acquisition systems.



Jean-Marc Chery, STMicroelectronics Conference Keynote: Embedded Intelligence for the Next Wave of Smart Systems – Opportunities and Challenges on the Edge February 27th, 2019, 1:30 PM

Jean-Marc Chery is STMicroelectronics' President and Chief Executive Officer since May 31st, 2018. In July 2017 Chery had been appointed Deputy CEO of ST with overall responsibility for Technology and Manufacturing, as well as for Sales and Marketing operations. Before that, he had held a broad range of management positions across ST functions throughout his career. Chery currently chairs the board of directors of STS, ST's manufacturing joint venture in China, and is a board member of the European microelectronics R&D program AENEAS.

OVERVIEW

5. Hardware Engineering		6. Software & Systems Engineering		7. Embedded Vision	8. Autonomous & Intelligent Systems	9. Embedded GUI & HMI	10. System-on-Chip										
Session 5.1: RISC-V I Overview	Class 5.1: Ultra Low Power	Session 6.1: SW- Engineering I Languages & Standards	Session 6.2 I: MISRA I	Class 6.1: The Bruce Douglass Class 1: Modeling		Session 7.1 I: Embedded Vision I	Session 8.1: Intelligent Systems I Applications										
Session 5.2: RISC-V II Security			Session 6.2 II: MISRA II			Session 7.1 II: Embedded Vision II	Session 8.2: Intelligent Systems II Hardware	Session 9.1: Embedded GUI & HMI									
Session 5.3: RISC-V III System								natuwate									
Class 5.2: RISC-V Workshop I		Session 6.3: SW- Engineering II	Class 6.2: The Bruce Douglass				Session 8.3: Intelligent Systems III		Session 10.1: SoC I Analog Circuits & Solutions								
		Design & Class 2 Modeling Agile	Class 2 Agile											Autonomous Driving		Session 10.2 I: SoC II EDA I	
Session 5.4: Power Supply		Session 6.4: SW- Engineering III SW-Quality I					Session 8.4: Intelligent Systems IV Development Methods		Session 10.2 II: SoC II EDA II								
		Session 6.5: SW- Engineering IV Development Process	Session 6.7: SW- Engineering VI SW-Testing	Class 6.3: The Bruce Douglass Class 3 Safety & Security	Class 6.4: The Greg Davis Class C / C++				Session 10.3: SoC III Complex Ics & System Solutions								
		Session 6.6: SW- Engineering V SW-Quality II	Session 6.8: SW- Engineering VII SW-Debugging						Session 10.4: SoC IV ICs & IPs								



Frank Riemenschneider, Publication Chair

Registered participants of the ewC2019 will receive the conference proceedings with the papers of selected contributions free of additional charge after the conference. The proceedings of ewC2018 reached nearly 1,000 pages with more than 170 papers.



TUESDAY, FEBRUARY 26, 2019

	Session 2.1: Communication I CAN	Session 3.1: OS Basics	Session 4.1 I: HW-based Security I	Session 4.2: Functional Safety
09:30-10:00	Troubleshooting in Embedded Networks Based on CANopen FD Reiner Zitzmann, CAN in Automation	Introduction to OpenAMP: An Open Source Standard and API for Asymmetric Multiprocessing Systems Jeffrey Hancock, Mentor, A Siemens Business	Hardware Security for Embedded Systems Ben Boehman, Advanced Micro Devices (AMD)	High Performance Distributed Mixed Criticality Systems to SIL2 Prof. Hans Dermot Doran, Zürich University of Applied Sciences
10:00-10:30	Automated Node ID Assignment in CAN and CAN(FD) Networks Christian Keydel, Olaf Pfeiffer, Embedded Systems Academy		Techniques for Securing Low-Cost Embedded Devices Josh Norem, Silicon Labs	Integrating Functional Safety Enabled 3rd Party IP Alexander Scheuermann, Texas Instruments
10:30-11:00	Signal Improvement Concept for CAN FD Networks Yao Yao, CAN in Automation	42 Reasons Using FreeRTOS Should Scare Developers Jacob Beningo, Beningo Embedded Group	Transitioning from Software Based Security to Hardware Based Security – How to Make the Leap Anthony Ambrose, Data I/O	Modeling and Assessment of Safety Critical Systems Thomas Barth, Hochschule Darmstadt
11:00-11:30		Coffee B	Ireak	
11:30-12:00	Session 2.2: Communication II Bluetooth Bluetooth Evolution Jim Katsandres, Bluetooth SIG	How to Measure RTOS Performance Colin Walls, Mentor, A Siemens Business	Making Products Safer and More Secure with an MPU Jean Labrosse, Silicon Labs	Safety Critical RTOS: Adapting Across Applications Andrew Longhurst, WITTENSTEIN high integrity systems
12:00-12:30	Supercharging BLE Beacons with Bluetooth 5 Joe Tillison, Silicon Labs	Home-grown or Commercial Linux: a Binary Choice? Iisko Lappalainen, MontaVista Software	Extend MCU Security Capabilities Beyond Trusted Execution with Hardware Crypto Acceleration and Asset Protection Saurin Choksi, NXP Semiconductors	Data and Control Coupling: Taint Analysis for Critical Embedded Applications Mark Pitchford, LDRA
12:30-13:30		Lunch B	reak	
13:30-14:30	KEYNOTE 13:30	Conference Developing Game-Changing Jim Tung, Ma	Embedded Intelligence	
	Session 2.3: Communication III Real-Time & TSN	Session 3.2: OSADL	Session 4.1 II: HW-based Security II	
14:30-15:00	Real-time Control of Embedded Devices with OPC UA Pub/Sub w, w/o TSN Heinrich Munz, KUKA	Performance of Real-time Computing and Real-time Network Communication Using the Linux Mainline Kernel in the OSADL QA Farm Dr. Carsten Emde, OSADL	What Can You Do When You Don't Trust Your Processor? Yoni Kahana, Nanolock security	
15:00-15:30	TSN – a Pragmatic Approach Michael Roeder, SILICA - Avnet EMG	Safe and Secure Field Updates of Embedded Linux Systems Enrico Jörns, Pengutronix	Methods for Provisioning Security Features in a Cortex-M33 based MCU Using a Physically Unclonable Function Rob Cosaro, NXP Semiconductors	
15:30-16:00		Coffee E	Break	
16:00-16:30	Time Sensitive Networking for Industry 4.0 and Automotive Dr. Dadmehr Rezaei, Intel	Using Linux in Safety-critical Environments: Update on the SIL2LinuxMP Project Prof. Nicholas Mc Guire, OpenTech EDV Research	Securing Edge Devices with Hardware-based Security Timo Grassmann, Infineon Technologies	
16:30-17:00	Extending Time Sensitive Networking over Next Generation Wi-Fi Ritu Sethi, Intel	Basics of Copyright Law and Open Source Licensing: Fulfilling License Obligations is Easier Than You May Think Dr. Carsten Emde, OSADL	Leverage Security IP Embedded in MCU for New Connectivity Use Cases Mayank Sharma, ARM	
17:00-17:30	SPICE Simulation of 100Base-TX LAN-Transformer in an Ethernet Transmission Path Simon Mark, Würth Elektronik eiSos	OSS Compliance Tools Dr. Michael Jaeger, Software Compliance Academy	Secure Boot of a Complex Quad Core CPU Ken Irving, Microchip Technology	
17:30-18:00		How to Implement Appropriate Processes for License Compliance? Dr. Catharina Maracke, Software Compliance Academy		

TUESDAY, FEBRUARY 26, 2019

Session 5.1: RISC-V I Overview	Session 6.1: SW-Engineering I Languages & Standards	Session 7.1 I: Embedded Vision I	Session 8.1: Intelligent Systems I Applications	
RISC-V; Practical Industry Approach to Getting Started with This Technology Prof. Robert Oshana, NXP Semiconductors	Declarative Programming for Cortex-M Class Embedded Devices Andy Walter, macio	Adding Intelligent Vision to Your Next Embedded Product Radhika Jagtap, ARM	The Edge is Getting Smarter – Al in the IoT World Amir Sherman, Arrow	
How to Benefit from RISC-V Based Linux for Embedded Industrial Applications Tim Morin, Microchip Technology	Navigating the Jungle of the Secure Coding Standards Michal Rozenau, Parasoft	Implementation of Camera Based Driver Monitoring System Using Deep Learning Nirmal Kumar Sancheti.	Context-Aware Smart Home – Opening the Eyes of Al in the Home Through Sensors Johan Pedersen, Silicon Labs	
This work, where the rechnology	Session 6.2 I: MISRA I	AllGo Systems	Johan Pedersen, Sincon Labs	
The Soul of a New SoC: Hands-on Experience with Embedding a RISC-V Core Onno Martens, Trinamic Motion Control	The MISRA C Coding Standard: A Key Enabler for the Development of Safety- and Security-Critical Embedded Software Roberto Bagnara, BUGSENG & University of Parma	Develop Multi-platform Computer Vision Solution with Intel Up Squared Oluwatobi Oyinlola, Intel	Ultra Low Power Key Phrase Detection at the Edge Hussein Osman, Lattice Semiconductor	
		Coffee Break		
Methodology for Implementation of Custom Instructions in the RISC-V Architecture Larry Lapides, Imperas Software	MISRA C/C++ Situation Report Andrew Banks, LDRA	High Image Quality for Embedded Vision Applications Henning Haider, Allied Vision Technologies	Embedded Deep Learning Healthcare Collaboration System Chungyeh Wang, Intel	
Compliance Methodology and Initial Results for RISC-V ISA Implementations Lee Moore, Imperas Software	Writing Reliable Code with MISRA C Colin Walls, Mentor, A Siemens Business	Machine Learning for Embedded; a System of Software and Hardware Components Prof. Robert Oshana, NXP Semiconductors	Motor Condition Monitoring for Predictive Maintenance in "Industrie 4.0" Volker Rzehak, Texas Instruments	

Lunch Break

Conference Keynote:

Developing Game-Changing Embedded Intelligence

Jim Tung, MathWorks

Session 5.2: RISC-V II Security	Session 6.2 II: MISRA II	Session 7.1 II: Embedded Vision II	Session 8.2: Intelligent Systems II Hardware	Session 9.1: Embedded GUI & HMI
Maintaining Security In a Heterogeneous and Changing World Jon Geater, Thales Cesare Garlati, prpl	Using MISRA C/C++ for Security and Reliability Greg Davis, Green Hills Software	Deep Learning Versus Rule- based-configurable Vision Software on Embedded Devices Christoph Wagner, MVTec Software	How to Implement Deep Learning on FPGAs Robert Green, Asic Design Services	Which Graphic Software Library Should I Use for My Embedded Device? Aurindam Jana, The Qt Company
A New Zero-Trust Model For Securing Embedded Systems Chris Conlon, wolfSSL Cesare Garlati, prpl	Avoiding Unsafe and Insecure Complex Software Mark Richardson, LDRA	Sorting Through the Many Options for Machine Learning at the Edge Markus Levy, NXP Semiconductors	Machine Learning on Arm Cortex-M Microcontrollers Dr. Naveen Suda, ARM	
		Coffee Break		
Session 5.3: RISC-V III System User Mode Interrupts: A Must for Securing Embedded Systems Prof. Sandro Pinto, Uni do Minho Cesare Garlati, prpl	Why Coding Standards and Implementing MISRA-C Chris Hills, Phaedrus Systems	Enhance Human Vision with Intel Vision Technology Pavani Kilari, Intel	Accelerating Next Generation Deep Learning Algorithms – How to Choose FPGA or GPU? Prof. Alok Gupta, Intel	Embedded Computer Vision Applications with Qt Berthold Krevert, basysKom
Embracing a System Level Approach: Combining Arm & RISC-V in Heterogeneous Designs Gajinder Panesar, UltraSoC	How Far Can You Trust Your Compiler? Mark Pitchford, LDRA	Implementing Monocular Visual SLAM for Augmented Reality in Low-Power Embedded Vision Systems Gordon Cooper, Synopsys	Hardware Implementation of Deep Neural Networks – A Comparison Between FPGA and GPU Marcus Rüb, Hahn-Schickard	3D GUIs for the Mass Market Jason Williamson, Altia
RISC-V Project: from Embedded Cores to Vision of Datacenter Processors Dr. Zvonimir Bandic, Western Digital	Approaches for Improving Handling of Static Analysis Findings Dr. Claude Bolduc, Rogue Wave Software	Bridging Embedded Vision and Machine Vision with a Hybrid Driver Mark Schenk, Allied Vision Technologies	Driving Deep Learning Performance Through Hardware Accelerators and Advanced Storage Technology Muhammad Waqas Sadiq Jutt, Intel	The Usage and Benefits of Global Palettes in Embedded Graphics Applications Kurt Parker, Microchip Technology
	powered by			

Want more? See page 12/13 for additional classes!

WEDNESDAY, FEBRUARY 27, 2019

	Session 1.1 I: Internet of Things I	Session 2.4: Communication IV Wireless Physical & Design Aspects	Session 3.3: Linux	Session 4.3 I: Security Architectures & Hacking I		
09:30-10:00	Session Keynote: Digital Transformation: A Catalyst for Changing the Embedded Development Paradigm Dr. Gareth Noyes, Wind River Systems	Model Based Approach for Wireless Network Design and Implementation Marco Roggero, MathWorks	ARM SoCs in the Mainline Linux Kernel Arnd Bergmann, Linaro	Lessons to be Learnt from the World's Most Lethal Cyber-Attacks Anyck Turgeo, IBM		
10:00-10:30	Think Local: How to Migrate Intelligence from the Cloud to Embedded Devices at the Edge Chris Shore, ARM	Robust Software Defined COFDM- Modem for Embedded Applications Andreas Bayer, A.R. Bayer DSP Systeme	Status of the Embedded GPU Space Robert Foss, Collabora	Quantum Computers Just Broke My Crypto – What Now? Kris Chaplin, Intel		
10:30-11:00	The Future of IoT: Edge Intelligence, Distributed Processing and Data Orchestration Olivier Pauzet, Sierra Wireless	From DC to Daylight: Single Chip RF Solutions for Wired, Wireless and High Frequency Applications Glenn Steiner, Xilinx	XDP for Embedded Networking Luka Perkov, Sartura	Breaking Security: Power Analysis & Fault Injection Attacks Dr. Colin O'Flynn, NewAE Technology/Dalhousie University		
11:00-11:30		Coffee	e Break			
11:30-12:00	Where the Cloud Meets the Edge Brad Cole, Digi International	How a Software-defined Radio Enables Diversity in IoT Endpoint Design Dan Clement, ON Semiconductor	Software Defined Peripherals in Linux Using Zephyr and RPMsg Marek Novak, NXP Semiconductors	Developing a Mixed-critical AUTOSAR Adaptive ECU with Safety and Security by Design Dr. Sergey Tverdyshev, SYSGO		
12:00-12:30	Distributed Database Systems and Edge/Fog/Cloud Computing Steve Graves, McObject	Introduction for Bluetooth5 IoT Device – RoKi Sensor Node Koki Okada, ROHM Semiconductor	Linux Containers on a Small Device – a Good Idea? Valter Minute, Toradex	Enabling TPM2.0 with an Open Source Software Stack for Industrial and Automotive Applications Dr. Florian Schreiner, Infineon Technologies		
12:30-13:30	12:30-13:30 Lunch Break					
13:30-14:30	Conference Keynote: KEYNOTE 13:30 Embedded Intelligence for the Next Wave of Smart Systems – Opportunities and Challenges on the Edge Jean-Marc Chery, STMicroelectronics					
	Session 1.1 II: Internet of Things II	Session 2.5: Communication V Wireless Multiprotocol	Session 3.4: Virtualization	Session 4.3 II: Security Architectures & Hacking II		
14:30-15:00	Databases at the Edge – ObjectBox for Devices and Gateways Markus Junginger, Objectbox	The Benefits and Challenges of a Common Software Platform for IoT Development David Egan, Silicon Labs	Virtualization Impact on the Performance in Embedded Systems Marcus Nissemark, Green Hills Software	Secure Boot, Chain of Trust and Data Protection Akshay Bhat, Timesys		
15:00-15:30	End-to-End Streaming Data Management Using Streaming Analytics Framework and Visual Data Management System Dr. Wendy Siew Wen Chin, Intel	Radio Scheduling in Dynamic Multiprotocol Applications Marius Munder, Silicon Labs	On the Road Towards Autonomous Driving – Simplifying AI with Virtualization Technologies Dr. Ciwan Gouma, OpenSynergy	Chains of Trust: Building Security into Today's Digital World Gil Bernabeu, GlobalPlatform		
15:30-16:00		Coffe	e Break			
16:00-16:30	Streaming Analytics Framework (SAF) Dr. Shao-Wen Yang, Intel	Low Power WiFi for IoT Devices Asaf Even-Chen, Texas Instruments	The Automotive GPU gets Virtual Kristof Beets, Imagination Technologies	Sidestepping Side Channel Attacks Through Separation & Virtualization Arun Subbarao, Lynx Software Technologies		
16:30-17:00	Towards a Greener World with ECMA-393 Network Proxying: A Practical Guide To Support Multi- Protocols Network Presence Boon Leong Ong, Intel	Manage Thousands of Nodes Through Secure Commissioning with Thread 1.2 Network Protocol Robert David, NXP Semiconductors	Handling Mixed Criticality on Modern Multi-core Systems: the HERCULES Project Dr. Paolo Gai, Evidence	Securing all Network Layers of CAN (FD) Communication Olaf Pfeiffer, Embedded Systems Academy Andreas Walz, HS Offenburg		
17:00-17:30	Applying Cognitive Systems Engineering to Shape a Good Developer Experience of IoT Solutions Dr. Jongsoon Park, Intel	Taking Mesh Networking Mainstream William Hart, Particle Industries	New Development Paradigms for Smart IoT Loïc Minier, Canonical	Simplifying Product Returns Through Device Security Øivind Loe, Silicon Labs		

WEDNESDAY, FEBRUARY 27, 2019

Session 6.3: Software Engineering II Design & Modeling	Session 8.3: Intelligent Systems III Autonomous Driving	Session 10.1: SoC I Analog Circuits & Solutions
Migrating Legacy Software Applications to Model-Based and AUTOSAR: an Introduction to a Programmatic Approach Roberto Agnelli, Teoresi	Law and Innovation – a Difficult Relationship? Susanne Meiners, NewTec	A Programmable Analog Computer on a Chip John Milios, Nicolas Clauvelin, Sendyne
Emerging MultiCore Development Paradigms Greg Davis, Green Hills Software	Performance Profiling and Optimization for Autonomous Driving Workload Yang Wang, Intel	Mission Impossible? If an Embedded Antenna Needs a Ground Plane of 100mm, How Can it Perform Brilliantly within an IoT Device with a Very Small PCB? Colin Newman, Antenova
Coping with Complexity in Mobility by Connected Model-based Systems Engineering – An Insight Look Into Successful Projects Andreas Korff, Parametric Technology	A Machine Learning Environment for Evaluating Autonomous Driving Software Jussi Hanhirova, Aalto University	Protect the Ports! George Slama, Wurth Elektronik eiSos
Coffe	e Break	
Software Quality, Systemic Failure and	Power Efficient AI Processors for	Session 10.2 I: SoC II EDA I
Dual Modular Redundancy Mark Pitchford, LDRA	Perception and Decision Making in Autonomous Vehicles Lazaar Louis, Cadence	Using Models for SoC Hardware/ Software Co-design Baruch Mitsengendler, MathWorks
Design Cycle Acceleration for Hardware/ Software Co-Design with Renode Dr. Greg Sullivan, Dover Microsystems	Understanding the Safe Move to Intended Functionality in Autonomy Joe Dailey, Mentor, A Siemens Business	Matlab Simulink for FPGA-Design Dr. Baltasar Trancón Widemann, aicas

Lunch Break

Conference Keynote:

Embedded Intelligence for the Next Wave of Smart Systems – Opportunities and Challenges on the Edge

Jean-Marc Chery, STMicroelectronics

	Session 5.4: Power Supply	Session 6.4: Software Engineering III Software Quality I	Session 8.4: Intelligent Systems IV Development Methods	Session 10.2 II: SoC II EDA II
	PoE: The Power Oriented Era Jairo Bustos Heredia, Würth Elektronik eiSos	Semantic Static Analysis of IoT Software Dr. Pietro Ferrara, JuliaSoft	Efficient Workflow for Designing, Training and Deploying Deep Learning Models with MATLAB Marco Roggero, The MathWorks	An Open Source Framework for Rapid Application Development for Complex SoCs Anton Krug, Microchip Technology
	Extending the Abilities of Battery- Powered End Nodes Through Better Power Supply Design Josh Norem, Silicon Labs	Static Analysis of Finite State Machines with Zero False Alarms Dr. Daniel Kästner, AbsInt Angewandte Informatik	Accelerating Embedded Inferencing Russell Klein, Mentor Graphics	Delivering Real Time and Determinism with Zynq Ultrascale+ MPSoC A53 Clusters Using Advanced Cache Management, Jailhouse and Xen Hypervisor Dr. Giulio Corradi, Xilinx
Coffee Break				
	OP-TEE – A Intro to a Trusted Execution Environment Andreas Schuler, Missing Link Electronics	Machine Learning for Finding Programming Defects and Anomalies Dr. Paul Anderson, GrammaTech	Benchmarking the Intelligent Edge – A Framework to Measure Embedded AI Performance Bruno Zimmermann, ZHAW InES	System-Level Modeling of Heterogeneous Compute Architectures for NVMExpress Protocol Acceleration Cedrik Bock, Missing Link Electronics
	Harvesting Energy from RS232 Data Signals to Power a Wired to Wireless Converter Prof. Dr. Marcel Meli, ZHAW InES	How to Find Concurrency Issues in C and C++ Dr. Frank van den Beuken, Perforce Software	Designing Intelligent Systems Using Resource Constrained Edge Devices Jacob Beningo, Beningo Embedded Group	Shifting-Left Together – Enabling the Ecosystem with Virtual Platforms Dr. Jakob Engblom, Intel
	Ferrite for EMC – What Do I Need to Know? George Slama, Wurth Elektronik eiSos	Automating Code Reviews by Writing Your Own Program Analysis Rules Prof. Dr. Ralf Huuck, Synopsys	Safety in Cooperative Automated Systems Dr. Daniel Schneider, Fraunhofer IESE	Shift Left for Software Development Using Virtual Platform Emulation Hybrids Frank Schirrmeister, Cadence Design Systems

Want more? See page 12/13 for additional classes!

THURSDAY, FEBRUARY 28, 2019

	Session 1.2: Internet of Things III	Session 2.6 I: NB-loT & LPWA I	Session 2.8 I: Wireless Power I	Session 3.5: OS-Security
09:30-10:00	IoT Platforms: Selection and Pitfalls Jan Rodig, tresmo	What 5G Can Help for Industrial IOT Yongbin Wei, Qualcomm Technologies	Market and Future of the Global Wireless Power Transfer Industry Jörg Hantschel, Würth Elektronik eiSos	The LTS Kernel is a Barrier to Building a Global Secure IoT Platform George Grey, Foundries.io
10:00-10:30	Benchmarks: the Good, the Bad, and the Ugly Diego Buitrago, Ben Boren, Intel	DECT-5G: Enhancing the DECT and ULE Standards to Embrace the Requirements of 5G (IMT-2020) Daniel Hartnett, DECT Forum	Qi Versus NFC: Evaluating NFC as a New Wireless Charging Solution for Small Battery Powered Devices Peter Schmallegger, NXP Semiconductors Austria	How Should an RTOS Works in a TrustZone for Armv8-M Environment? Joseph Yiu, ARM
10:30-11:00	How the Use the IIC's IICF to Select the Best IIoT Connectivity Technology Brett Murphy, Real Time Innovations	Evaluating NB-IoT Technology for Industrial Communication Kofi Atta Nsiah, Hahn-Schickard	EMF: Requirements, Directives and Measure Method in Europe Werner Grommes, DGUV/IFA	Designing a Secure and Reliable OTA Update Mechanism for IoT Endpoints Nick Lethaby, Texas Instruments
11:00-11:30		Coffee	e Break	
11:30-12:00	IoT Device Lifecycle Management – Update. Control. Secure. The Keys to IoT Device Best Performance and Secure Data-to-cloud Connections Francis D'Souza, Gemalto	LoRa LoRaWAN a Technologie Used in Industrial Application Michael Fink, Semtech Germany	15W Inductive Wireless Power Transfer with Integrated Data Communication Cem Som, Würth Elektronik eiSos	Android Security Internals Karim Yaghmour, Opersys
12:00-12:30	Improving Reliability of Industrial IoT Systems Edwin de Jong, Real Time Innovations	The 20 Cent IoT is Coming Aurelius Wosylus, Sigfox Germany	Boosting Contactless Charging to 40W Francois Ricodeau, Semtech	A Future-proof Performance Enhancement for Secure MCUboot Derek Atkins, SecureRF
12:30-13:30		Lunch	n Break	
	Session 1.3: Internet of Things IV OPC UA I4.0	Session 2.6 II: NB-loT & LPWA II	Session 2.8 II: Wireless Power II	
13:30-14:00	Open Source OPC UA Pub/Sub Over TSN: Current Status and Implementation Plans Julius Pfrommer, Fraunhofer IOSB	Revolutionizing Worker Safety with Innovative IoT and LPWAN Solutions Albert Behr, Behr Technologies	Regulatory Requirements for Devices Using Wireless Power Transfer Technology	
			Niels Jeß, CETECOM	
14:00-14:30	OPC UA Application Development with Open62541 Frank Meerkötter, basysKom	Unified Test Environment for LPWA and Cellular IoT Jubin E. Sebastian, Offenburg University of Applied Sciences	5,	
14:00-14:30 14:30-15:00	with Open62541	and Cellular IoT Jubin E. Sebastian,	Niels Jeß, CETECOM Wireless Power Transfer Safety Test Toolkit: An Automated Tool for Compliance Testing of WPT Systems Including Implant Safety	
	with Open62541 Frank Meerkötter, basysKom Dynamic LWM2M Data Model Mapping to OPC UA	and Cellular IoT Jubin E. Sebastian, Offenburg University of Applied Sciences	Niels Jeß, CETECOM Wireless Power Transfer Safety Test Toolkit: An Automated Tool for Compliance Testing of WPT Systems Including Implant Safety Dr. Ilaria Liorni, IT'IS Foundation Wireless Power Transfer in Rotating Assemblies Jelena Mijuskovic,	
14:30-15:00	with Open62541 Frank Meerkötter, basysKom Dynamic LWM2M Data Model Mapping to OPC UA	and Cellular IoT Jubin E. Sebastian, Offenburg University of Applied Sciences	Niels Jeß, CETECOM Wireless Power Transfer Safety Test Toolkit: An Automated Tool for Compliance Testing of WPT Systems Including Implant Safety Dr. Ilaria Liorni, IT'IS Foundation Wireless Power Transfer in Rotating Assemblies Jelena Mijuskovic, Würth Elektronik eiSos	

THURSDAY, FEBRUARY 28, 2019

Session 4.4 I: Securing IoT I	Session 6.5: Software Engineering IV Development Process	Session 6.7: Software Engineering VI Software Testing	Session 10.3: SoC III Complex ICs & System Solutions	
Common Pitfalls in IoT Security Implementations and How to Avoid Them Brent Wilson, Silicon Labs	Agile in Development Regarding Safety Frank Poignée, infoteam Software	Self-testing in Embedded Systems Colin Walls, Mentor, A Siemens Business	Next Generation 7nm FPGA Architecture Enables Machine Learning for Edge and Cloud Computing Manoj Roge, Achronix Semiconductor	
Security on IoT Devices with Secure Elements Tobias Schläpfer, ZHAW Institute of Embedded Systems	Adopting Agile/DevOps ALM in Automotive & Safety-critical Development Peter Haller, Intland Software	Testing Strategies for Asymmetric Environments Jeffrey Fortin, Vector Informatik	Design Space Exploration for Convolutional Neural Networks on a 22nm FD-SOI SoC Nicolai Behmann, Leibniz Universität Hannover	
Finding the Right Security Level for Your IoT Application Dr. Lars Lydersen, Silicon Labs	How to Balance Traceability and Compliance With Agile Development Robert Riccetti, Gerhard Kruger, Perforce Software	Testing Safety Critical Software Using Automated Fault Injection Michael Wittner, Razorcat Development	High Performance Thermal Management Using Miniature Low Cost Microfluidics Heat Sink Philippe Soussan, IMEC	
	Coffe	ee Break		
Optimizing Threat Modelling to Create Robust IoT Security Solutions Suresh Marisetty, ARM	Open Source Software and Mission- Critical Embedded Systems – Like Oil and Water Andrew Banks, LDRA	Hardware in the Loop Test in Combination with Continuous Integration Dr. Kristian Trenkel, iSyst Intelligente Systeme	400G+ Hyperscale Data Centers with 56G Ethernet PHY IP Manmeet Walia, Synopsys	
Secure Device Management for the Internet of Things Geert-Jan Schrijen, Intrinsic ID	Bug-killing Using Best-practice Development Techniques Mark Richardson, LDRA	Consistent Test Reuse Across MIL->SIL ->HIL in a Model-Driven Development Workflow Lance Brooks, Mentor, A Siemens Business	SSD SoC Microcontroller with Embedded Neural Network for 3D NAND Flash Memories Dr. Lorenzo Zuolo, Microsemi	
	Lunc	h Break		
Session 4.4 II: Securing IoT II	Session 6.6: Software Engineering V Software Quality II	Session 6.8: Software Engineering VII Software Debugging	Session 10.4: SoC IV ICs & IPs	
Make Your IoT Project Secure in 5 Steps Dr. Shawn Prestridge, IAR Systems	The (Software) Doctor is inSoftware Vital Signs for Managing the Development of Your Embedded Software Prof. Robert Oshana, NXP Semiconductors	Tips and Tricks for Debugging Greg Davis, Green Hills Software	RADAR Signal Processing on an Embedded System Using the Xilinx Zynq Platform Prof. Frank Kesel, Hochschule Pforzheim	at 05.12.2018)
A Major New IoT Security Certification Scheme with Innovative Trust Signals – PSA Certified Robert Coombs, ARM	Miscompilation – A Thing of the Past Dr. Daniel Kästner, AbsInt Angewandte Informatik		Lowering Software Development Costs by Using Arm Cortex-M Processors in an FPGA Phillip Burr, ARM	Program is subject to change (as at 05.1
Secure and Scalable FW Upgrade Mechanisms in the IoT Domain Frank Audun Kvamtrø, Nordic Semiconductor	Uncovering Real-Time Bugs with Specialized RTOS Tools Jean Labrosse, Silicon Labs	Simplify Multi-core Debugging in Your SoC Development Workflow Dr. Shawn Prestridge, IAR Systems	Custom RF SoC Have Never Been this Easy Edel Griffith, Adesto Technologies	Program
	Coffe	ee Break		
Security and Licensing for IoT Devices Guenther Fischer, Wibu-Systems	Safety, Security, and Compiler Bugs Greg Davis, Green Hills Software	Connectivity, Complexity & the Role of Enhanced Debugging Trish Messiter, Clarinox Technologies	Virtual Digital Sensor for Analog Signal Processing on SoCs Vinay Bansal, Faststream Technologies	
Why Should an IoT Sensor Maker Care About the Blockchain? Mark Hebbel, Basler	The AMASS Approach for Assurance and Certification of Critical Systems Gaël Blondelle, Eclipse Foundation Europe		High Speed Communication: Everything Serial Dirk van den Heuvel, Topic Embedded Products	

Want more? See page 12/13 for additional classes!

TUESDAY, FEBRUARY 26, 2019

	Class 3.1: The Robert Berger Class – Embedded Linux	Class 5.1: Ultra Low Power Class	Class 6.1: The Bruce Douglass Class 1 – Modeling
09:30-10:30	Embedded Linux a Crash Course Robert Berger, Reliable Embedded Systems	Ultra Low Power Hands-on Workshop Herman Roebbers, Altran	Model-Based Interface Control Documents
10:30-11:00			Improving System Requirements with Use Case Models
11:30-12:30			Everything you Always Wanted to Know About Flowcharts and Activity Diagrams
14:30-15:30			Advanced Behavioral Modeling with State Machines
16:00-17:00			Data Modeling for Systems Engineering and System Specification
17:00-17:30			The Tao of SysML Dr. Bruce Douglass, IBM

WEDNESDAY, FEBRUARY 27, 2019

	Class 3.2: Embedded Android Workshop	Class 3.3: Linux Hands-on Workshop with BeagleBoard.org PocketBeagle	Class 4.1: The ESCRYPT Class
09:30-10:30	Embedded Android Workshop Karim Yaghmour, Opersys		The ESCRYPT Class – Security for a Globally Connected Vehicle ESCRYPT, et.al.
10:30-11:00			
11:00-11:30			
11:30-12:00			
12:00-12:30			
14:30-15:30		Getting Started with PocketBeagle from BeagleBoard.org – A Hands-On Coding with Embedded Linux Workshop	
15:30-16:00		Jason Kridner, Texas Instruments & BeagleBoard.org Foundation	
16:00-17:30			

THURSDAY, FEBRUARY 28, 2019

	Class 3.4: The Mc Guire Class: Introduction to Linux Kernel Tools	Class 4.2: Hands on Side Channel Power Analysis	Class 6.3: The Bruce Douglass Class 3 Safety & Security
09:30-10:15	OSADL: Introduction to Linux Kernel Tools Prof. Nicholas Mc Guire, Markus Kreidl, OSADL powered by		Safety Analysis for Embedded Systems Development
10:15-10:30			
10:30-11:00			Safety Design for Embedded Systems Development
11:00-11:15			
11:30-12:00			Model-Based Systems Engineering for Cybersecurity
12:00-12:30			Dr. Bruce Douglass, IBM
13:30-16:30		Hands on Side Channel Power Analysis Dr. Colin O'Flynn, NewAE Technology/Dalhousie University	

www.embedded-world.eu



Class 5.2: RISC-V Workshop	Class 6.2: The Bruce Douglass Class 2 Agile
How to Build a RISC-V Embedded System In Just 30 Minutes Cesare Garlati, prpl Foundation	Agile Systems Engineering
How to Secure a RISC-V Embedded System In Just 30 Minutes Don Barnetson, Zorlu Ventures	
Cesare Garlati, prpl Foundation	
	Agile for Safety Critical Systems: Design Practices
Trusted Execution Environments: A System Design Perspective Boran Car, Hex Five Security Cesare Garlati, prpl Foundation	
	Agile for Safety Critical Systems: Quality Assurance Practices
	Agile for Safety Critical Systems: Evidence-Oriented Practices Dr. Bruce Douglass, IBM

Class 6.4: The Greg Davis Class C / C++

Writing Reliable and Portable C/C++ Code

Understand Shared Memory in the C/C++ Standards

Porting C Code to C++ Code

Hack-Proofing Your C/C++ Code Greg Davis, Green Hills Software

embedded world Conference 2019 – Embedded Intelligence

Classes:

In the embedded world Classes, reputed experts speak on special topics for half a day or a full day. This format is aimed primarily at participants who want to familiarize themselves thoroughly and efficiently with a specific topic. Straightforward and concise dialogues with the experts help to answer many questions and are an excellent opportunity of quickly expanding your current expertise. The classes aim at maximum learning goals.

With these equally compact and concentrated classes, the embedded world Conference covers a broad range of substantial aspects of embedded systems in detail to offer developers competent technical groundwork.

Be sure to register now!



Exhibition&Conference

Venue: NürnbergMesse Messezentrum NCC Ost 90471 Nuremberg, Germany

Details and Registration: www.embedded-world.eu

Thursday, Feb 28, 2019	
am pm	

Class Fees	Early Rate until January 17, 2019	Late Rate from January 18, 2019
Half Day Class	EUR 380,-	EUR 440,
Full Day Class	EUR 570,	EUR 650,
Conference Fees	Early Rate until January 17, 2019	Late Rate from January 18, 2019
1 Conference Block	EUR 325,—	EUR 370,—
2 Conference Blocks	EUR 445,—	EUR 500,—
3 Conference Blocks	EUR 560,—	EUR 640,
4 Conference Blocks	EUR 660,—	EUR 750,
5 Conference Blocks	EUR 745,—	EUR 845,—
Full Conference (Classes excluded)	EUR 790,	EUR 910,

All fees plus 19% VAT

* Please note: In order to be registered you have to fill in all required fields marked with an asterisk (*). (A confirmation email will be sent to you.) If yot want to state a different billing-address: Please register online.

l am	Exhibitor	Student	Co-Speaker (with)
Company				
Mr./Ms./Title*Fir	st Name*Last Name*			- hibition-
Street/No.*Depa	rtment			Exhibition- Ticket included!
ZIP-Code*City*C	ountry*			included!
Phone*E-Mail*				

Date/Signature*

Register online: www.embedded-world.eu or send this fax registration form to + 49 (0) 89 / 255 56 – 0155

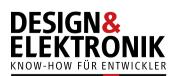
Please make sure that you are sending both pages!

Please tick:				
SESSIONS Tuesda Feb 26, 2			Wednesday, Feb 27, 2019	Thursday, Feb 28, 2019
	world Conference 2019	Block 1 Block 2	Block 3 Block 4	Block 5 Block 6
		am pm	am pm	am pm
Session 1.1 I/II:	Internet of Things I/II			
Session 1.2:	Internet of Things III			
Session 1.3:	Internet of Things IV OPC UA I4.0			
Session 2.1:	Communication I CAN			
Session 2.2:	Communication II Bluetooth			
Session 2.3:	Communication III Real-Time & TSN			
Session 2.4:	Communication IV Wireless Physical & Design Aspects			
Session 2.5:	Communication V Wireless Multiprotocol			
Session 2.6 I/II:	NB-IOT & LPWA I/II			
Session 2.7:	Communication VI Wireless Localization			
Session 2.8 I/II:	Wireless Power I/II			
Session 3.1:	OS Basics			
Session 3.2:	OSADL			
Session 3.3:	Linux			
Session 3.4:	Virtualization			
Session 3.5:	OS-Security			
Session 4.1 I/II: Session 4.2:	HW-based Security I/II Functional Safety			
Session 4.2 I/II:	Security Architectures & Hacking I/II			
Session 4.4 I/II:	Security Architectures a nacking init			
Session 5.1:	RISC-V I Overview			
Session 5.2:	RISC-V II Security			
Session 5.3:	RISC-V III System			
Session 5.4:	Power Supply			
Session 6.1:	SW-Engineering I Languages & Standards			
Session 6.2 I/II:	MISRA I/II			
Session 6.3:	Software Engineering II Design & Modeling			
Session 6.4:	Software Engineering III Software Quality I			
Session 6.5:	Software Engineering IV Development Process			
Session 6.6:	Software Engineering V Software Quality II			
Session 6.7:	Software Engineering VI Software Testing			
Session 6.8:	Software Engineering VII Software Debugging			
Session 7.1 I/II:	Embedded Vision I/II			
Session 8.1:	Intelligent Systems I Applications			
Session 8.2:	Intelligent Systems II Hardware			
Session 8.3:	Intelligent Systems III Autonomous Driving			
Session 8.4:	Intelligent Systems IV Development Methods			
Session 9.1:	Embedded GUI & HMI			
Session 10.1:	SoC I Analog Circuits & Solutions			
Session 10.2 I/II:	SoC II EDA I/II			
Session 10.3:	SoC III Complex ICs & System Solutions			
Session 10.4:	SoC IV ICs & IPs			

Terms and Conditions:

1. The attendance fee includes participation on the booked conference days, proceedings, refreshments and free admission to the embedded world 2019 Exhibition. If morning and afternoon blocks/classes are booked, lunch is also included for that day.

- 2. You will receive a confirmation of your conference registration along with your invoice.
- 3. Cancellations received in writing before or on February 05, 2019 will be subject to a service charge of EUR 50 for one-day registrations and EUR 100 for several-days registrations. For all cancellations received after February 05, 2019 the full conference fee remains payable. Substitutions within the same company are welcome at any time.
- 4. The organizers reserve the right to make changes in the program and/or speakers or to cancel sessions/classes if conditions beyond its control prevail. Please check www.embedded-world.eu for the latest conference information.
- 5. Students are granted a 50 % reduction, student ID required. Please submit by fax to + 49 (0) 89 / 255 56 0155 or by email to JHeger@weka-fachmedien.de.
- 6. Exhibitors or Co-Speakers will receive a discount of 50 % limited to one person.
- 7. For registrations of five persons and more from one company, please contact our conference department for special rates.
- 8. On-site-registration: Please register in advance. For on-site-registration a surcharge of EUR 70 per attendee will apply.



design-elektronik.de

Contact: Ms. Juliane Heger Phone: +49 (0) 89 / 255 56 - 1155 Email: JHeger@weka-fachmedien.de WEKA FACHMEDIEN GmbH Richard-Reitzner-Allee 2 85540 Haar, Germany

An Excellent





Coupled Inductors

The WE-MCRI is an innovative molded coupled inductor with fully automated bifilar winding process. It offers an almost ideal coupling coefficient up to 0.995. The WE-MCRI features a soft saturation behavior with its crystalline core structure and distributed air gap. The coupled inductor range includes high voltage isolation versions up to 2 kV, low profile types and versions with various turns ratios.

For further information, please visit: www.we-online.com/coupled





WE-CPIR HV









WE-TDC

Low

Profile



High

WE-CEWI

High Saturation Current

#INDUCTORDUET WE speed up the future

- Up to 0.995 coupling coefficient
- Up to 2.0 kV isolation
- Soft saturation
- Up to 120 A I_{SAT} and 48 A I_{R}
- Large portfolio

WE-MCBI

WF-FHPI

WE-DCT